日本インター株式会社

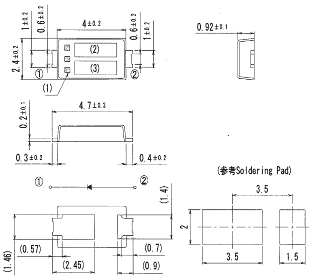
Nihon Inter Electronics Corporation

5A Avg. 120 Volts SBD NA05HSA12

■最大定格 Maximum Ratings

Item	Symbol	Conditions			Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	120			V
平均整流電流 Average Rectified Forward Current	I_O	50Hz、正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	Ta=30℃* V_{RM}=60V	1.2	A
			Tl=91℃ V_{RM}=60V (Tl:lead Temperature)	5.0	A
実効順電流 R.M.S. Forward Current	$I_{F(RMS)}$	7.85			A
サージ順電流 Surge Forward Current	I_{FSM}	100 50Hz正弦半波，１サイクル，非くり返し 50Hz Half Sine Wave,1cycle, Non-repetitive			A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	−40～＋150			℃
保存温度範囲 Storage Temperature Range	T_{stg}	−40～＋150			℃

■OUTLINE DRAWING(mm)



■APPROX. NET WEIGHT:0.03 g

■電気的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions		Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	T_j=25℃, V_{RM}=120V		—	—	100	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	T_j=25℃, I_{FM}=5A		—	—	0.86	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	＊（ガラエポ基板実装）	—	—	130	℃/W
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—		—	13	℃/W

＊プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands= 2.0 × 1.5 mm, 2.0 × 3.5 mm)

■定格・特性曲線

FIG.1
順電圧特性
FORWARD CURRENT VS. VOLTAGE

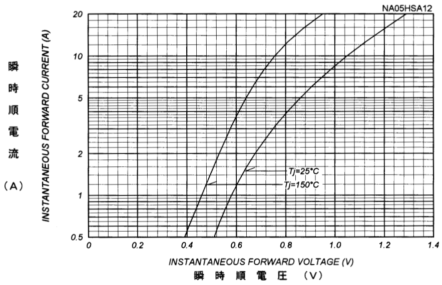


FIG.2
平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

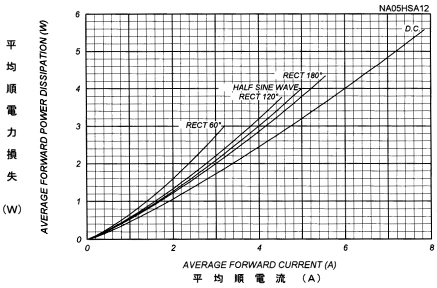


FIG.3
ピーク逆電流 － ピーク逆電圧特性
PEAK REVERSE CURRENT VS. PEAK REVERSE VOLTAGE

Tj= 150 °C

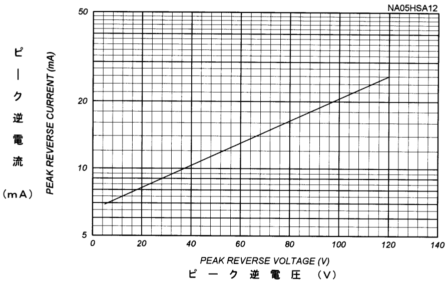


FIG.4
平均逆電力損失
AVERAGE REVERSE POWER DISSIPATION

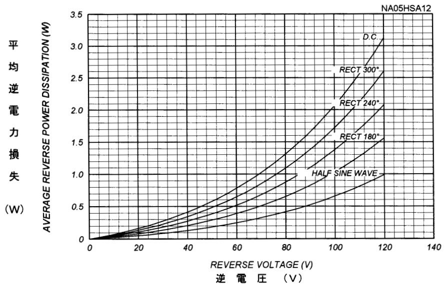


FIG.5
平均順電流－リード温度定格
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

V_{RM}=60V

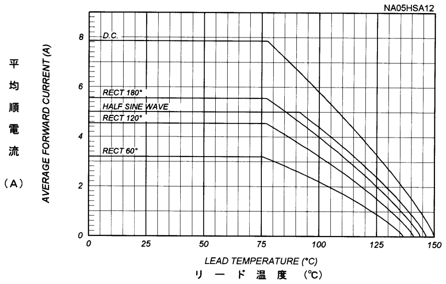


FIG.6
平均順電流－周囲温度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Glass-Epoxy Substrate Mounted (Soldering Land=2.0×1.5mm,2.0×3.5mm),V_{RM}=60V

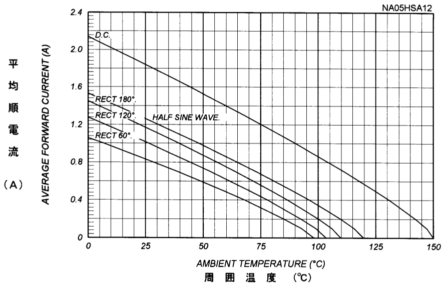


FIG.7
サージ順電流定格
SURGE CURRENT RATINGS

f=50Hz,Half Sine Wave,Non-Repetitive,No Load

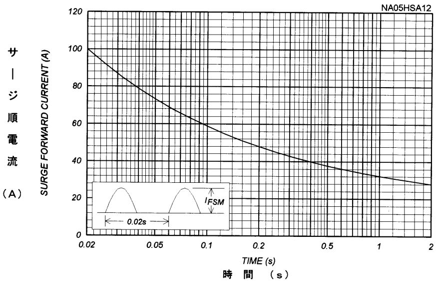


FIG.8
接合容量特性
JUNCTION CAPACITANCE VS. REVERSE VOLTAGE

Tj=25°C,Vm=20mV$_{RMS}$,f=100kHz,Typical Value